

## **AMENDMENTS TO THE CLAIMS**

1 to 19. (Canceled)

20. (New) A copper-based alloy containing Bi, Pb and 0.01 to 1.0 weight% of Te, said Te forming, in an alloy texture, an intermetallic compound of Pb-Te, said intermetallic compound having a higher melting point than a Bi-Pb binary eutectic crystal.

21. (New) The copper-based alloy according to claim 20, containing Te at 0.01 to 0.22 weight%.

22. (New) The copper-based alloy according to claim 20, containing at least Sn at 2.8 to 6.0 weight%, Zn at 1.0 to 12.0 weight% and Bi at 0.1 to 3.0 weight%.

23. (New) The copper-based alloy according to claim 22, containing at least Sn at 2.8 to 6.0 weight%, Zn at 1.0 to 12.0 weight% and Bi at 0.1 to 3.0 weight%.

24. (New) The copper-based alloy according to claim 20, containing at least Sn at 2.8 to 6.0 weight%, Zn at 1.0 to 12.0 weight%, Bi at 0.1 to 2.4 weight% and Se at 0.05 to 1.2 weight%.

25. (New) The copper-based alloy according to claim 22, containing at least Sn at 2.8 to 6.0 weight%, Zn at 1.0 to 12.0 weight%, Bi at 0.1 to 2.4 weight% and Se at 0.05 to 1.2 weight%.

26. (New) The copper-based alloy according to claim 20, which has a Pb content of not more than 0.25 weight%.

27. (New) The copper-based alloy according to claim 21, which has a Pb content of not more than 0.25 weight%.

28. (New) The copper-based alloy according to claim 22, which has a Pb content of not more than

0.25 weight%.

29. (New) The copper-based alloy according to claim 23, which has a Pb content of not more than 0.25 weight%.

30. (New) The copper-based alloy according to claim 24, which has a Pb content of not more than 0.25 weight%.

31. (New) The copper-based alloy according to claim 25, which has a Pb content of not more than 0.25 weight%.